

OXFORD ICP RIE BOSCH 418441

 Villach

BRIEF DESCRIPTION

Bosch dry etching Tool. 8" wafers etch with ESC clamping. 6" and 4" wafers with mechanical clamp configuration.

RESEARCH SERVICES

- Cavities/Cap etching for MEMS applications
- High aspect ratio etching
- Continuous mixed Si etching for shallow (~1µm) features
- SiO₂ and SiN_x etching

METHODS & EXPERTISE ON THE RESEARCH INFRASTRUCTURE

The PlasmaPro®100 Cobra is a modular plasma processing etch tool. A large range of options is available to precisely tailor the tool to the customer's requirements. The tool features a small footprint and a semi-automatic loading system. The PlasmaPro®100 Cobra can process a wide range of wafer sizes, from small wafer pieces up to 200 mm (8") diameter.

CONTACT

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